

# **4V Drive Nch MOSFET**

# RSD050N10

#### Structure

Silicon N-channel MOSFET

#### Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 3) Parallel use is easy.

# Applications

Switching

Packaging specifications

	Package	CPT3				
Type	Code	TL				
	Basic ordering unit (pieces)	2500				

# ● Absolute maximum ratings (T<sub>a</sub>=25°C)

Paran	Symbol	Symbol Limits		
Drain-source voltage		$V_{DSS}$	100	V
Gate-source voltage		$V_{GSS}$	±20	V
Drain current	Continuous	I <sub>D</sub>	±5.0	Α
	Pulsed	I <sub>DP</sub> *1	±20	Α
Source current	Continuous	Is	5.0	Α
(Body Diode)	Pulsed	I <sub>SP</sub> *1	20	Α
Power dissipation		P <sub>D</sub> *2	15	W
Channel temperature		T <sub>ch</sub>	150	°C
Range of storage temperature		T <sub>stg</sub>	-55 to +150	°C

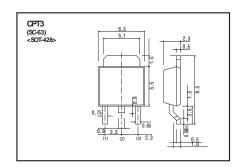
<sup>\*1</sup> Pw≦10μs, Duty cycle≦1%

#### ●Thermal resistance

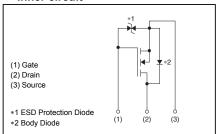
Parameter	Symbol	Limits	Unit
Channel to Case	R <sub>th (ch-c)</sub> *	8.33	°C/W

<sup>\*</sup> T<sub>c</sub>=25°C

#### • Dimensions (Unit : mm)



# • Inner circuit



<sup>\*2</sup> T<sub>c</sub>=25°C

Data Sheet

# ●Electrical characteristics (T<sub>a</sub>=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	-	-	±10	μA	$V_{GS}$ =±20V, $V_{DS}$ =0V
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	1	-	10	μA	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	1.0	-	2.5	V	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA
Otatia daria an anatata	*	-	135	190		I <sub>D</sub> =5.0A, V <sub>GS</sub> =10V
Static drain-source on-state resistance	R <sub>DS (on)</sub>	-	142	200	mΩ	I <sub>D</sub> =5.0A, V <sub>GS</sub> =4.5V
resistance		-	145	205		I <sub>D</sub> =5.0A, V <sub>GS</sub> =4.0V
Forward transfer admittance	IY <sub>fs</sub> I*	2.5	-	-	S	I <sub>D</sub> =5.0A, V <sub>DS</sub> =10V
Input capacitance	C <sub>iss</sub>	-	530	-	pF	V <sub>DS</sub> =25V
Output capacitance	C <sub>oss</sub>	-	50	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	1	30	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	1	10	-	ns	I <sub>D</sub> =2.5A, V <sub>DD</sub> ≒ 50V
Rise time	t <sub>r</sub> *	-	15	-	ns	V <sub>GS</sub> =10V
Turn-off delay time	t <sub>d(off)</sub> *	-	45	-	ns	$R_L$ =20 $\Omega$
Fall time	t <sub>f</sub> *	-	15	-	ns	$R_G$ =10 $\Omega$
Total gate charge	Q <sub>g</sub> *	-	14	-	nC	V <sub>DD</sub> ≒ 50V
Gate-source charge	Q <sub>gs</sub> *	-	1.7	-	nC	I <sub>D</sub> =5.0A,
Gate-drain charge	Q <sub>gd</sub> *	-	3.0	-	nC	V <sub>GS</sub> =10V

<sup>\*</sup>Pulsed

# ●Body diode characteristics (Source-Drain) (T<sub>a</sub>=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	V <sub>SD</sub> *	-	-	1.2	V	I <sub>s</sub> =5.0A, V <sub>GS</sub> =0V

<sup>\*</sup>Pulsed

#### ●Electrical characteristic curves (T<sub>a</sub>=25°C)

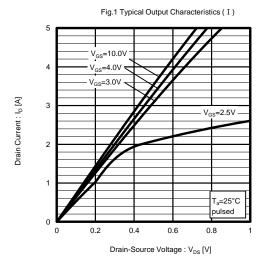


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

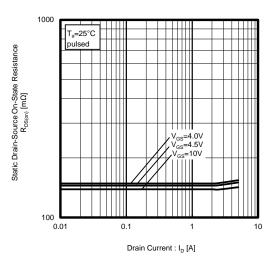


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

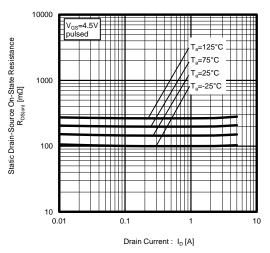


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

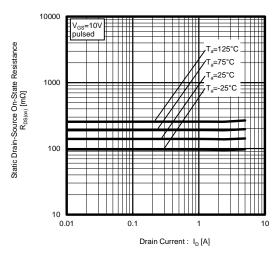


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current

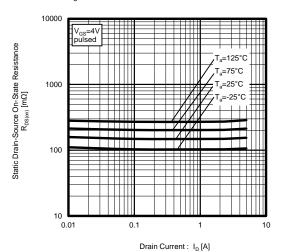


Fig.7 Forward Transfer Admittance vs. Drain Current

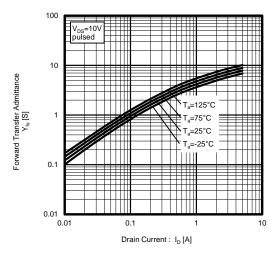


Fig.9 Source Current vs. Source-Drain Voltage

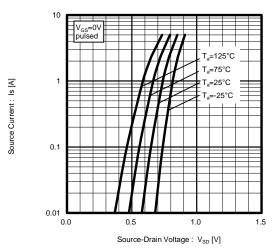


Fig.11 Switching Characteristics

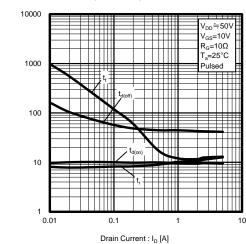


Fig.8 Typical Transfer Characteristics

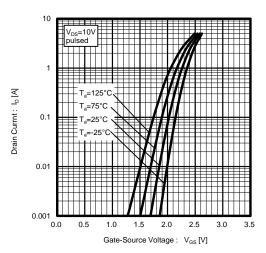


Fig.10 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

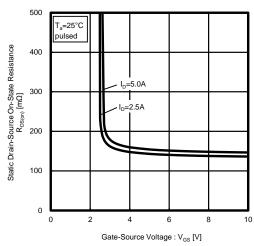
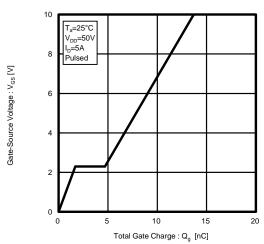


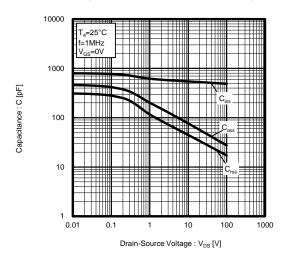
Fig.12 Dynamic Input Characteristics



Switching Time : t [ns]

Normalized Transient Thermal Resistance: r(t)

Fig.13 Typical Capacitance vs. Drain-Source Voltage



Drain Current: Ip [A]

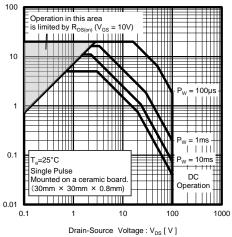
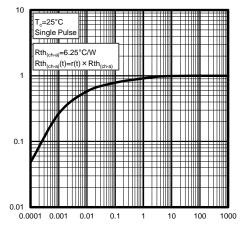


Fig.14 Maximum Safe Operating Area

Fig.15 Normalized Transient Thermal Resistance v.s. Pulse Width



Pulse width: Pw (s)

Data Sheet

# Measurement circuits

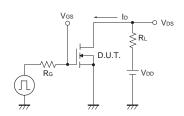


Fig.1-1 Switching time measurement circuit

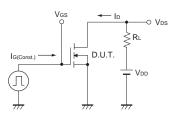


Fig.2-1 Gate charge measurement circuit

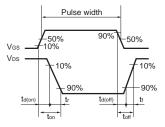


Fig.1-2 Switching waveforms

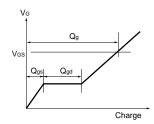


Fig.2-2 Gate Charge Waveform

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